

EXPOSED LEAD INTERPOSER FRAME PACKAGE

ABSTRACT OF THE INVENTION

[0087] An interposer for use in an external lead or land pattern semiconductor package. The interposer includes an interposer body which is molded from a dielectric material. The interposer body defines opposed top and bottom surfaces, an outer peripheral edge, and an inner peripheral edge. Embedded within the interposer body is a die pad which itself defines opposed top and bottom surfaces and a peripheral edge. The bottom surface of the die pad is exposed in and substantially flush with the bottom surface of the interposer body, with the inner peripheral edge of the interposer body and the top surface of the die pad collectively defining a cavity of the interposer. A plurality of electrically conductive interposer leads are embedded within the top surface of the interposer body and at least partially exposed therein. The interposer body forms a nonconductive barrier between each of the interposer leads and between the interposer leads and the die pad.